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post cover 2454. Actuation of the cantilever arm actuator 2457 provides pivotal movement, as indicated by arrow A2 of the cantilever arm 2456 about the pivot joint 2459. Retracting the cantilever arm actuator 2457 results in the cantilever arm 2456 moving the head assembly 2410 away from the process cell 420, shown in FIG. 6. Moving the head assembly from the process cell provides spacing to remove and/or replace the process cell 420 from the electroplating process cell 240. When the head assembly is removed from the process cell, the substrate can be inserted into or removed from the head assembly. Rotating the head assembly 2410 about the pivot joint 2459 results in the substrate being angled relative to the electrolyte cell. When the cantilever arm actuator 2457 is extended, the cantilever arm 2456 moves the head assembly 2410 toward the process cell 420 to position the substrate in the head assembly 2410 in a processing position.

IN THE CLAIMS:

Please cancel claims 1-3, 7-9, 13-15, 18-21 and 24 without prejudice.

Please amend the following claims:

1. (Cancelled) An apparatus for electro-chemically depositing a metal film on a substrate having a metal seed layer, comprising:
  - a substrate holder for holding the substrate;
  - an electrolyte cell for receiving the substrate in a processing position; and
  - an actuator connected to the substrate holder for adjustably positioning the substrate relative to the electrolyte cell to provide a desired uniformity of metal film deposition depth.
2. (Cancelled) The apparatus of claim 1, further comprising a metal deposition portion that provides for deposition of the metal film on the seed layer on the substrate.
3. (Cancelled) The apparatus of claim 1, wherein the adjustably positioning comprises displacing the substrate holder in a substantially vertical direction.

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4. (Amended) An apparatus for electro-chemically depositing a metal film on a seed layer disposed on a substrate, comprising: